



**SLOVENSKI STANDARD
SIST EN IEC 62037-1:2022**

01-marec-2022

**Nadomešča:
SIST EN 62037-1:2012**

Pasivne radiofrekvenčne (RF) in mikrovalovne naprave, meritve intermodulacijskega nivoja - 1. del: Splošne zahteve in merilne metode (IEC 62037-1:2021)

Passive RF and microwave devices, intermodulation level measurement - Part 1: General requirements and measuring methods (IEC 62037-1:2021)

Passive HF- und Mikrowellenbauteile, Messung des Intermodulationspegels - Teil 1: Allgemeine Anforderungen und Messverfahren (IEC 62037-1:2021)

Dispositifs RF et à micro-ondes passifs, mesure du niveau d'intermodulation - Partie 1: Exigences générales et méthodes de mesure (IEC 62037-1:2021)

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Ta slovenski standard je istoveten z: EN IEC 62037-1:2021

ICS:

33.120.30 Radiofrekvenčni konektorji RF connectors
(RF)

SIST EN IEC 62037-1:2022 **en**

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EUROPEAN STANDARD

EN IEC 62037-1

NORME EUROPÉENNE

EUROPÄISCHE NORM

December 2021

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Supersedes EN 62037-1:2012 and all of its amendments
and corrigenda (if any)

English Version

Passive RF and microwave devices, intermodulation level
measurement - Part 1: General requirements and measuring
methods
(IEC 62037-1:2021)

Dispositifs RF et à micro-ondes passifs, mesure du niveau
d'intermodulation - Partie 1: Exigences générales et
méthodes de mesure
(IEC 62037-1:2021)

Passive HF- und Mikrowellenbauteile, Messung des
Intermodulationspegels - Teil 1: Allgemeine Anforderungen
und Messverfahren
(IEC 62037-1:2021)

This European Standard was approved by CENELEC on 2021-12-23. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 62037-1:2021 (E)**European foreword**

The text of document 46/834/FDIS, future edition 2 of IEC 62037-1, prepared by IEC/TC 46 “Cables, wires, waveguides, RF connectors, RF and microwave passive components and accessories” was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62037-1:2021.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2022-09-23
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2024-12-23

This document supersedes EN 62037-1:2012 and all of its amendments and corrigenda (if any).

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Any feedback and questions on this document should be directed to the users' national committee. A complete listing of these bodies can be found on the CENELEC website.

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The text of the International Standard IEC 62037-1:2021 was approved by CENELEC as a European Standard without any modification.

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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 62037	series	Passive RF and microwave devices, EN IEC 62037 intermodulation level measurement	EN IEC 62037	series

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INTERNATIONAL STANDARD

NORME INTERNATIONALE



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**Passive RF and microwave devices, intermodulation level measurement –
Part 1: General requirements and measuring methods**

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**Dispositifs RF et à micro-ondes passifs, mesure du niveau d'intermodulation –
Partie 1: Exigences générales et méthodes de mesure**

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CONTENTS

FOREWORD	3
1 Scope	5
2 Normative references	5
3 Terms, definitions and abbreviated terms	5
3.1 Terms and definitions	5
3.2 Abbreviated terms	5
4 Characteristics of intermodulation products	6
5 Principle of test procedure	6
6 Test set-up	6
6.1 General	6
6.2 Test equipment	7
6.2.1 General	7
6.2.2 Set-up 1	7
6.2.3 Set-up 2	8
7 Preparation of DUT and test equipment	8
7.1 General	8
7.2 Guidelines for minimizing generation of passive intermodulation	8
8 Test procedure	9
9 Reporting	10
9.1 Results	10
9.2 Example of results	10
10 Measurement error	10
Annex A (informative) Configuration of low-PIM termination	13
A.1 General	13
A.2 Configuration of low-PIM terminations	13
A.2.1 Long cable termination	13
A.2.2 Lumped termination with a linear attenuator	13
Annex B (informative) Test procedure considerations	15
B.1 PIM variation versus frequency	15
B.2 Stepped frequency sweep method	15
B.3 Fixed frequency method	15
B.4 Dynamic PIM testing	15
B.5 Heating effects	15
Figure 1 – Set-up 1: reverse IM-test set-up	11
Figure 2 – Set-up 2: forward IM-test set-up	11
Figure 3 – Passive intermodulation (PIM) measurement error caused by residual system error	12
Figure A.1 – Long cable termination	13
Figure A.2 – Lumped termination with a linear attenuator	14
Table 1 – Guide for the design, selection of materials and handling of components that can be susceptible to PIM generation	9
Table 2 – Test set-up conditions	10

INTERNATIONAL ELECTROTECHNICAL COMMISSION

**PASSIVE RF AND MICROWAVE DEVICES,
INTERMODULATION LEVEL MEASUREMENT –****Part 1: General requirements and measuring methods**

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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IEC 62037-1 has been prepared by IEC technical committee 46: Cables, wires, waveguides, RF connectors, RF and microwave passive components and accessories. It is an International Standard.

This second edition cancels and replaces the first edition published in 2012. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) clarification added that test equipment may utilize pulsed generators to reduce power consumption;
- b) heating effect differences in the device under test noted in Annex B for tests conducted using pulsed generators;
- c) guidance added in Annex B to improve probability of detection of short duration PIM events while dynamic testing.

The text of this International Standard is based on the following documents:

Draft	Report on voting
46/834/FDIS	46/855/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

This International Standard is to be used in conjunction with IEC 62037 (all parts).

A list of all the parts in the IEC 62037 series, published under the general title *Passive RF and microwave devices, intermodulation level measurement*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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PASSIVE RF AND MICROWAVE DEVICES, INTERMODULATION LEVEL MEASUREMENT –

Part 1: General requirements and measuring methods

1 Scope

This part of IEC 62037 deals with the general requirements and measuring methods for intermodulation (IM) level measurement of passive RF and microwave components, which can be caused by the presence of two or more transmitting signals.

The test procedures given in this document give the general requirements and measurement methods required to characterize the level of unwanted IM signals using two transmitting signals.

The IEC 62037 series addresses the measurement of PIM, but does not cover the long-term reliability of a product with reference to its performance.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 62037 (all parts), *Passive RF and microwave devices, intermodulation level measurement*

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3 Terms, definitions and abbreviated terms

3.1 Terms and definitions

No terms and definitions are listed in this document.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

3.2 Abbreviated terms

CATV	Community antenna television
CFEC	Carbon fibre epoxy composite
CW	Continuous wave
DUT	Device under test
IM	Intermodulation
PCB	Printed circuit board
PIM	Passive intermodulation
RBW	Resolution bandwidth
VDA	Vacuum deposited aluminium